

LINEAR TECHNOLOGY MATERIALS DECLARATION

1t3065emse-2.5#pbf

(Engineering Calculation)

MSOP-Exposed

(printed on: 2020-07-11 20:26:52)

TOTAL MASS (g) : 0.036538

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.002111 | 1000000 | 57775.4296875 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.013845 | 975000 | 378920.34375 | | |
| | | Iron (Fe) | 7439-89-6 | 0.000341 | 24000 | 9332.74316406 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000004 | 300 | 109.474998474 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000010 | 700 | 273.687469482 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.014200 | 1000000 | 388636.21875 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.000710 | 1000000 | 19432.4941406 | | |
| | | External Plating Total: | | | | 0.000710 | 1000000 | 19432.4941406 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000086 | 1000000 | 2353.71240234 | | |
| Internal Plating Total: | | | | 0.000086 | 1000000 | 2353.71240234 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.000364 | 820000 | 9962.22558594 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000080 | 180000 | 2189.49975586 | | |
| Die Attach Total: | | | | 0.000444 | 1000000 | 12151.7246094 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.001932 | 103000 | 52876.4257812 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.016790 | 895000 | 459521.3125 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000038 | 2000 | 1040.01245117 | | |
| | | Encapsulation Total: | | | | 0.018760 | 1000000 | 513437.75 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000227 | 1000000 | 6212.70556641 | | |
| | | | | | TOTAL MASS (g) : | 0.036538 | | |